

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Feng Wei Kuo</td> <td>07/31/2012</td> </tr> <tr> <td>Huan-Neng Chen</td> <td>07/30/2012</td> </tr> <tr> <td>Chewn-Pu Jou</td> <td>07/30/2012</td> </tr> <tr> <td>Shou-Mao Chen</td> <td>07/30/2012</td> </tr> <tr> <td>Der-Chuang Yeh</td> <td>08/02/2012</td> </tr> </tbody> </table>		Name	Execution Date	Feng Wei Kuo	07/31/2012	Huan-Neng Chen	07/30/2012	Chewn-Pu Jou	07/30/2012	Shou-Mao Chen	07/30/2012	Der-Chuang Yeh	08/02/2012
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Der-Chuang Yeh	08/02/2012												
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State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13557457</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13557457								
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Application Number:	13557457												
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ATTORNEY DOCKET NUMBER:	TSMCP151US												

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NAME OF SUBMITTER:

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Total Attachments: 7

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U.S. Patent Appln. No.

Docket No. TSMCP151US

Filing Date:

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

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AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

“A BAND PASS FILTER FOR 2.5D / 3D INTEGRATED CIRCUIT APPLICATIONS”

for which:

U.S. Patent Appln. No.

Docket No. TSMCP151US

Filing Date:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

was filed on _____ and accorded U.S. Serial No. _____; or

will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes and requests ASSIGNEE'S legal representatives, the attorneys associated with Customer No. _____, to insert below in this document this APPLICATION's U.S. Serial Number and filing date, when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise,

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said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

✓ 2012/07/31
Date

✓ Feng - Wei Kuo
Name 1st Inventor Feng Wei Kuo

TSMC Docket No. TSMC2012-0214

Docket No. TSMCP151US

U.S. Patent Appl. No.

Filing Date:

✓ 2012/07/30
Date

✓ Huan-Neng Chen
Name 2nd Inventor Huan-Neng Chen

TSMC Docket No. TSMC2012-0214

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Filing Date:

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✓ Chewn-Pu Jou
Name 3rd Inventor

TSMC Docket No. TSMC2012-0214

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✓ 2012/07/30
Date

✓ Shuo-mao Chen
Name 4th Inventor Shuo-Mao Chen

TSMC Docket No. TSMC2012-0214

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Filing Date:

✓ 08/02/2012
Date

✓ 
Name 5th Inventor Der-Chyang Yeh